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Part Number: [0878251001](#)
Status: **Active**
Description: 1.27mm (.050") Pitch DDR DIMM Socket, 25 Degree Angle, Through Hole, 2.5V Right Voltage Keys, 2.79mm(.110") Tail Length, 100 Circuits, 0.38µm (15µ") Selective Gold(Au) Plating, Lead-free

Documents:

[3D Model](#) [RoHS Certificate of Compliance \(PDF\)](#)
[Drawing \(PDF\)](#)

Agency Certification

CSA 19980
 UL E29179

General

Product Family Memory Module Sockets
 Series [87825](#)
 Comments Latches in Biege ColorPeg Length at 3.18mm (.125")
 Component Type Memory Module
 JEDEC Outline MO-161
 Product Name DDR DIMM

Physical

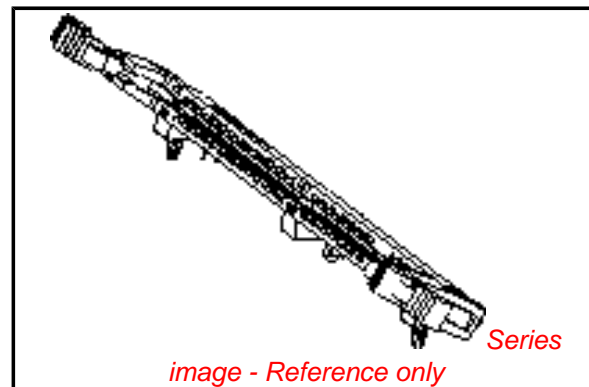
Circuits (Loaded) 100
 Color - Resin Black, Natural
 Durability (mating cycles max) 25
 Entry Angle 25° Angle
 Flammability 94V-0
 Keying to Mating Part Yes
 Material - Metal Phosphor Bronze
 Material - Plating Mating Gold
 Material - Plating Termination Tin
 Material - Resin High Temperature Thermoplastic
 PC Tail Length (in) 0.110 In
 PC Tail Length (mm) 2.79 mm
 PCB Locator Yes
 PCB Retention Yes
 PCB Thickness Recommended (in) 0.062 In
 PCB Thickness Recommended (mm) 1.60 mm
 Packaging Type Tray
 Pitch - Mating Interface (in) 0.050 In
 Pitch - Mating Interface (mm) 1.27 mm
 Plating min: Mating (µin) 15, 15.2
 Plating min: Mating (µm) 0.38
 Plating min: Termination (µin) 100, 101.6
 Plating min: Termination (µm) 2.54
 Temperature Range - Operating -40°C to +85°C
 Termination Interface: Style Through Hole

Electrical

Current - Maximum per Contact 1A
 Voltage - Maximum 50V
 Voltage Key 2.5V, Right

Solder Process Data

Duration at Max. Process Temperature (seconds) 10



EU RoHS

ELV and RoHS Compliant
REACH SVHC Contains SVHC: No
Halogen-Free Status

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

[87825Series](#)

Mates With

JEDEC MO-161 modules

Lead-free Process Capability	SMC & Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	1
Process Temperature max. C	265

Material Info

Reference - Drawing Numbers

Sales Drawing	SD-87825-001
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This document was generated on 04/13/2010

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E E

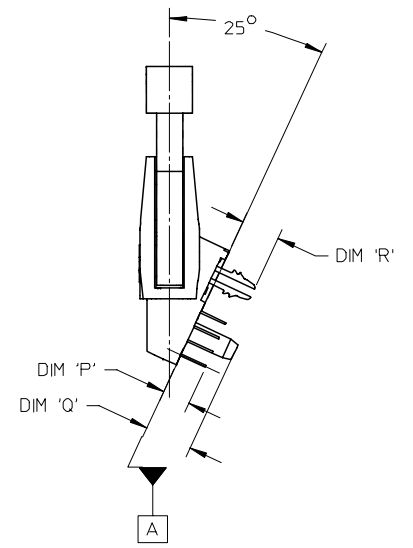
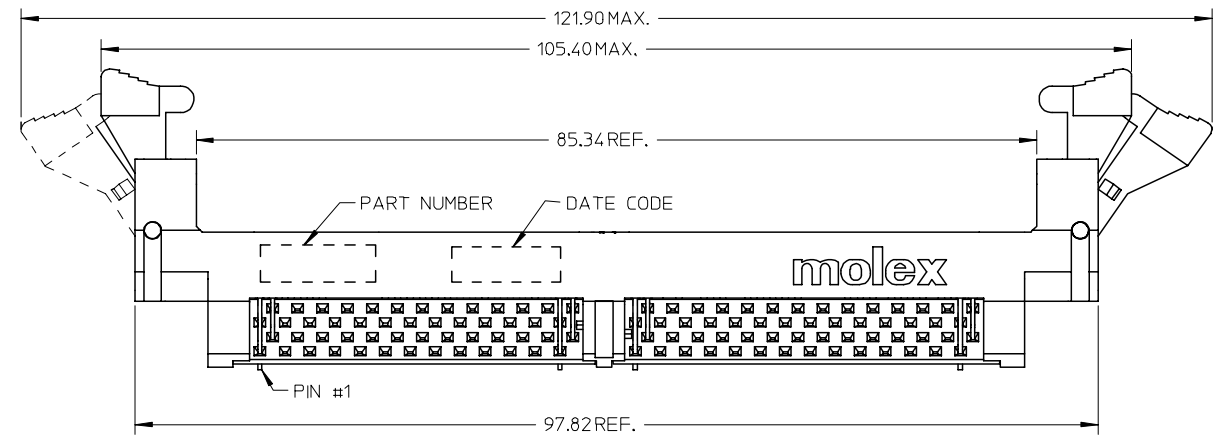
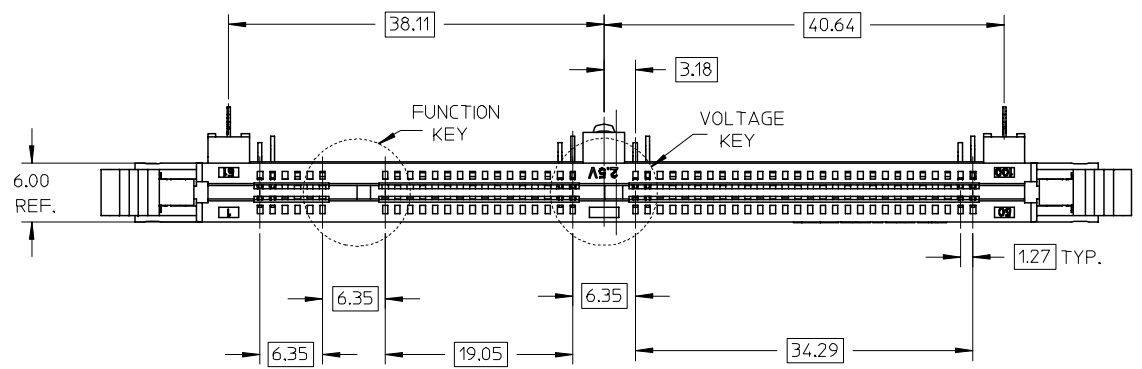
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C C

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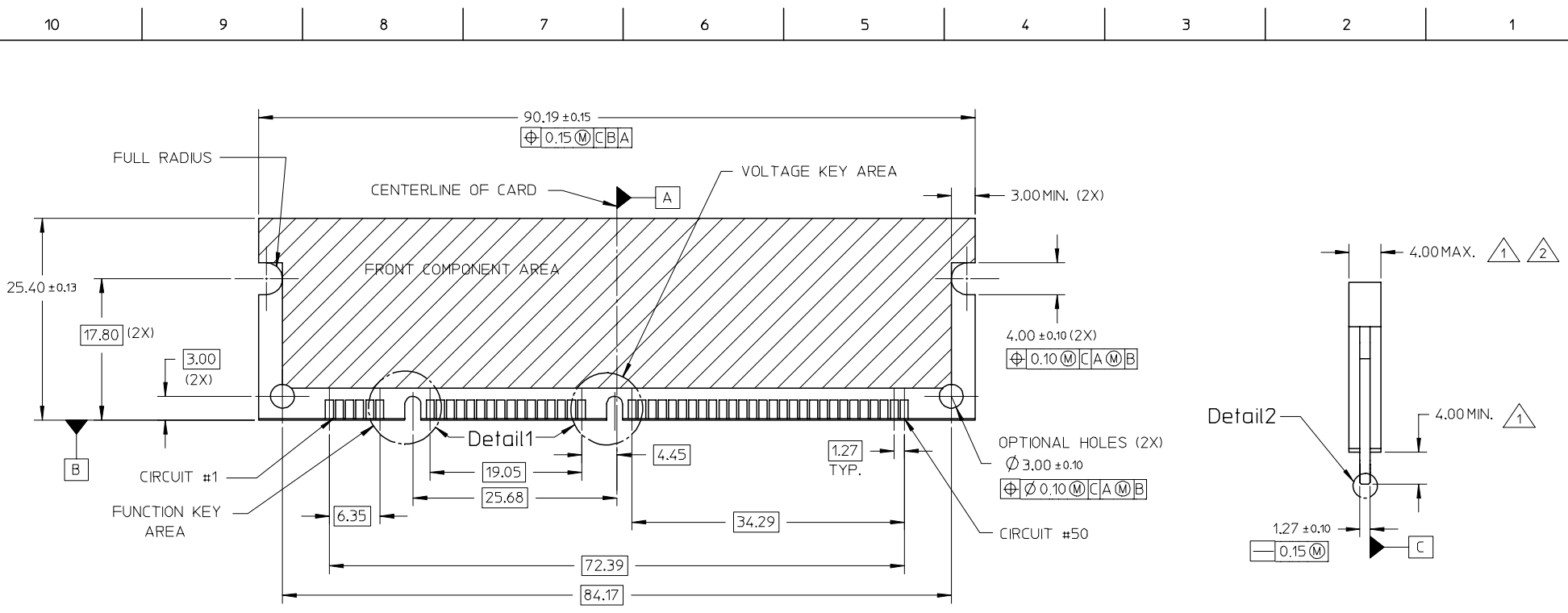
A A

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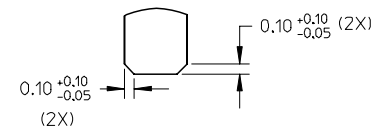
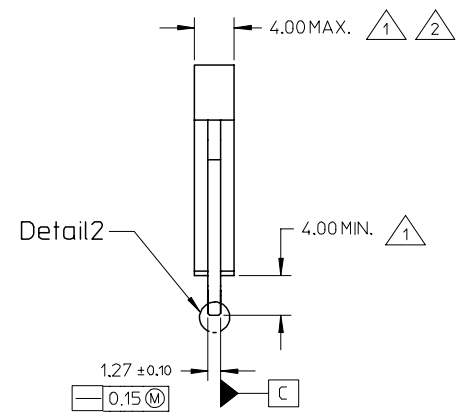
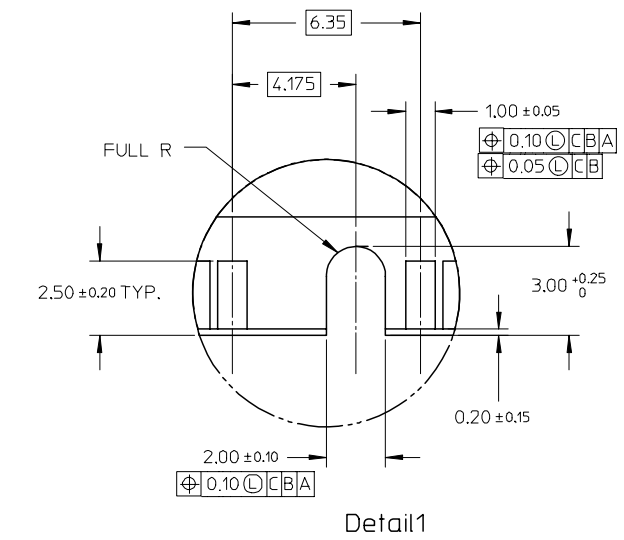


- NOTES:**
- MATERIALS: HOUSING AND BASEPLATE - LCP, GLASS FILLED, UL 94V-0, COLOR: BLACK
LATCH - HIGH TEMP NYLON, GLASS FILLED, UL 94V-0, COLOR : BEIGE
TERMINAL AND FORKLICK - COPPER ALLOY
 - FINISHES: CONTACT AREA: SEE TABLE IN SHEET 4
SOLDERTAILS: 2.54uM/100u" MIN. TIN
 - SEE PRODUCT SPECIFICATIONS: PS-87825-002 FOR PERFORMANCE SPECIFICATIONS
 - DATE CODE SHALL BE MARKED LEGIBLY AS SHOWN: YY DDD
 - PART NUMBER SHALL BE MARKED LEGIBLY AS SHOWN: 87825-XXXX

OBS TIN/LEAD P/N EC NO: S2006-0758 DRWN:MLONG 2006/03/31 CHKD:ARJUGHAM 2006/03/31 APPR:GGLLEE 2006/03/31	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
				DRAWN BY VSKHOANG	DATE 2003/09/24	TITLE DDR DIMM, 1.27MM PITCH 100 CKTS, 25 DEG					
				CHECKED BY MLONG	DATE 2003/11/13	APPROVED BY SKTOH		DATE 2003/11/13	MOLEX INCORPORATED		
				ANGULAR ± 5 °		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-87825-001	SHEET NO. 1 OF 4		
D	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



RECOMMENDED MODULE LAYOUT
(PER JEDEC STANDARD MO-161, 100CKT)



NOTES:
 1 DIMENSION APPLICABLE WHEN COMPONENTS MOUNTED ON BOTH SIDES.
 2 WHEN SOJ DEVICES ARE USED FOR ASSEMBLY OF THIS MODULE, THE MAXIMUM THICKNESS OVERALL SHALL NOT EXCEED 9.00MM. WHEN TSOP DEVICES ARE USED, MAXIMUM THICKNESS SHALL NOT EXCEED 4.00MM.

OBS TIN/LEAD P/N EC NO: S2006-0758 DRWN:MLONG 2006/03/31 CHKD:ARJUGHAM 2006/03/31 APPR:GGLLEE 2006/03/31	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY VSKHOANG	DATE 2003/09/24	TITLE DDR DIMM, 1.27MM PITCH 100 CKTS, 25 DEG			
		4 PLACES ± ---	± ---		CHECKED BY MLONG	DATE 2003/11/13				
		3 PLACES ± ---	± ---		APPROVED BY SKTOH	DATE 2003/11/13				
			2 PLACES ± 0.25	± ---		MOLEX INCORPORATED				
			1 PLACE ± ---	± ---		DOCUMENT NO. SD-87825-001				
			ANGULAR ± 5 °		MATERIAL NO.		SHEET NO. 2 OF 4			
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE					
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

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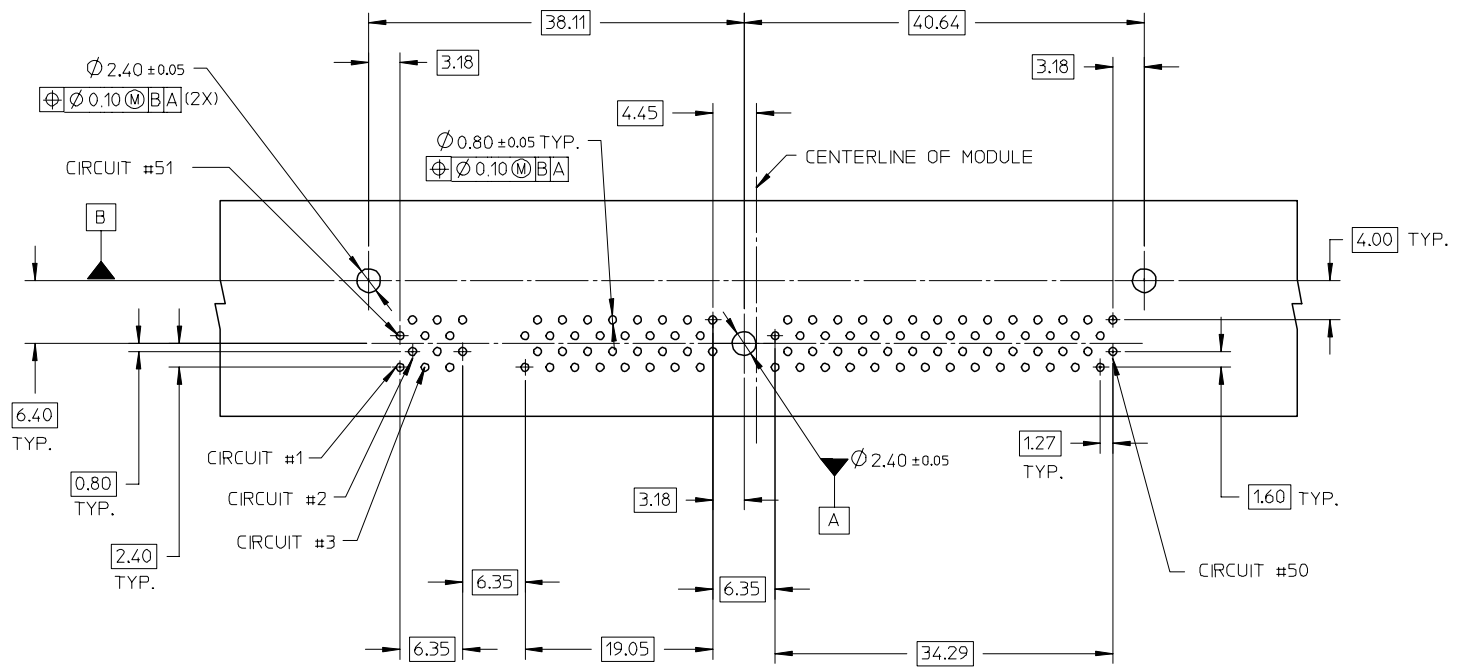
E E

D D

C C

B B

A A



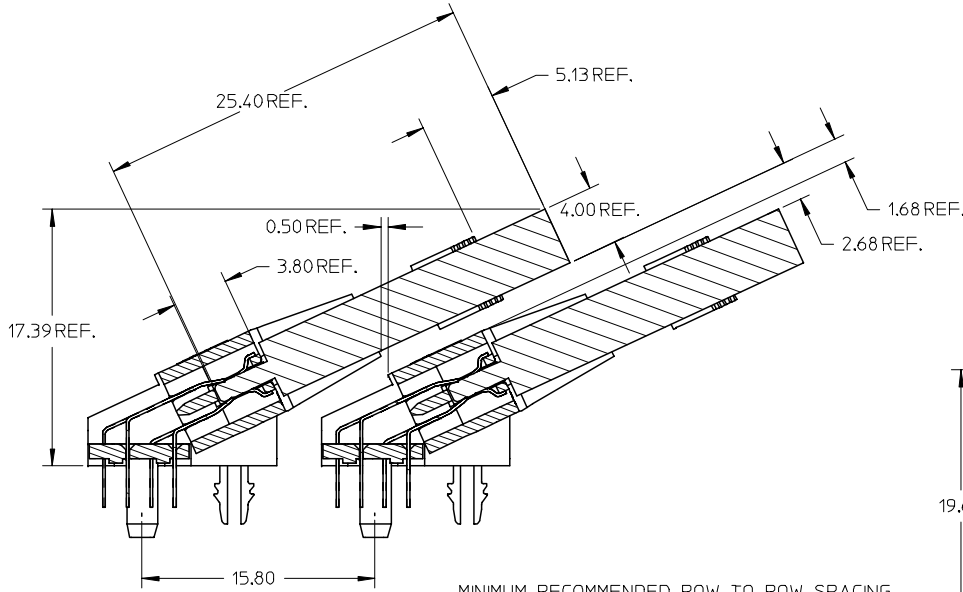
RECOMMENDED P.C. BOARD
HOLE PATTERN
(CONNECTOR SIDE)

OBS TIN/LEAD P/N EC NO: S2006-0758 DRWN:MLONG CHKD:ARJUGHAM APPR:GJLEE	2006/03/31 2006/03/31 2006/03/31 2006/03/31	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			$\nabla=0$ $\sphericalangle=0$	mm	INCH	DRAWN BY VSKHOANG	DATE 2003/09/24	TITLE DDR DIMM, 1.27MM PITCH 100 CKTS, 25 DEG				
			4 PLACES ± ---	± ---	CHECKED BY MLONG	DATE 2003/11/13	APPROVED BY SKTOH		DATE 2003/11/13	MOLEX INCORPORATED		SHEET NO. 3 OF 4
			3 PLACES ± ---	± ---	MATERIAL NO.		DOCUMENT NO.		SD-87825-001			
2 PLACES ± 0.25	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE								
1 PLACE ± ---	± ---			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						
ANGULAR ± 5 °												

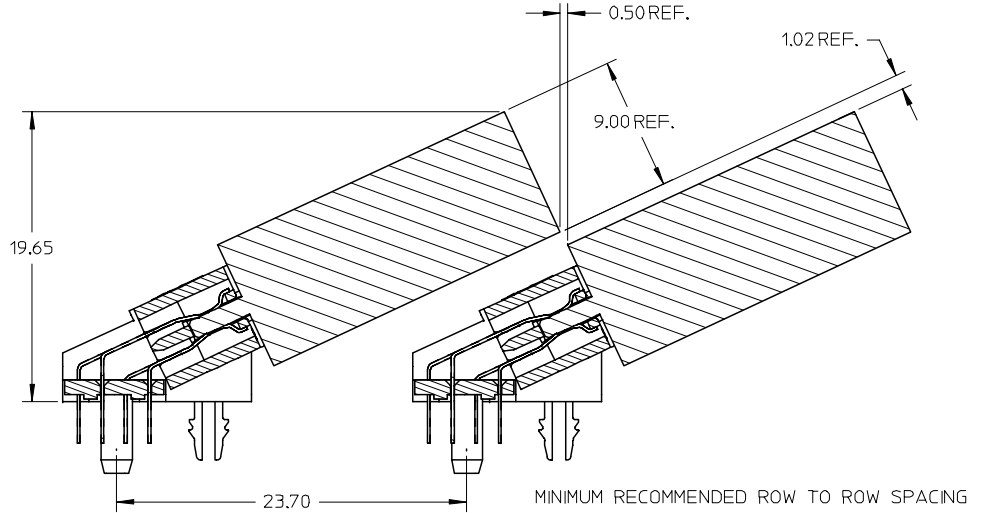
9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

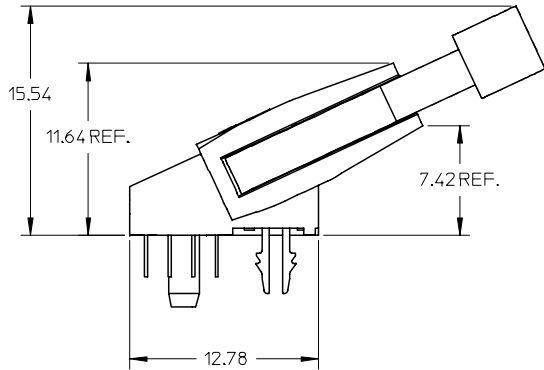
PART NO.	VOLTAGE KEY	CKT SIZE	TAIL LENGTH P±0.25	PEG LENGTH Q±0.25	FORKLOCK LENGTH R±0.25	RECOMMENDED PCB THICKNESS	FINISHES: CONTACT AREA	FINISHES: SOLDERTAIL
87825-1001	RIGHT (2.5V)	100	2.79	3.18	3.94	1.57	SELECTIVE GOLD 0.38µM/15µ" MIN. GOLD OVER 1.27µM/50µ" MIN. NICKEL	2.54µM/100µ" MIN. TIN OVER 1.27µM/50µ" MIN. NICKEL
87825-1011			3.18	4.83				



MINIMUM RECOMMENDED ROW TO ROW SPACING
WHEN USING A 4.00MM THICK
MODULE (TYPICAL TSOP PACKAGING)



MINIMUM RECOMMENDED ROW TO ROW SPACING
WHEN USING A 9.00MM THICK
MODULE (TYPICAL SOJ PACKAGING)



OBS TIN/LEAD P/N EC NO: S2006-0758 DRWN:MLONG CHKD:ARJUGHAM APPR:GJLEE	2006/03/31	2006/03/31	2006/03/31
	2006/03/31	2006/03/31	2006/03/31
	2006/03/31	2006/03/31	2006/03/31
	2006/03/31	2006/03/31	2006/03/31

QUALITY SYMBOLS	DESCRIPTION
▽=0	
▽C=0	

GENERAL TOLERANCES (UNLESS SPECIFIED)	
	MM ONLY
	INCH
4 PLACES	± ---
3 PLACES	± ---
2 PLACES	± 0.25
1 PLACE	± ---
ANGULAR ± 5 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE	
MM ONLY	
DRAWN BY	DATE
VSKHOANG	2003/09/24
CHECKED BY	DATE
MLONG	2003/11/13
APPROVED BY	DATE
SKTOH	2003/11/13
MATERIAL NO.	
SEE TABLE	

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
NTS	METRIC	
TITLE		
DDR DIMM, 1.27MM PITCH 100 CKTS, 25 DEG		
MOLEX INCORPORATED		
DOCUMENT NO.	SHEET NO.	
SD-87825-001	4 OF 4	

9 8 7 6 5 4 3 2 1